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(54) **DEVICE FOR PRODUCING MULTI-LAYER
CIRCUIT BOARDS AND USE THEREOF IN A
MULTI-LEVEL HEAT PRESS**

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(57) **ABSTRACT**

A device for producing multi-layer circuit boards, comprising a multi-part tool having a tool lower part and a tool upper part. In the intended use of the tool, multiple functional layers and at least one insulating layer of a multi-layer circuit board to be produced are arranged between the tool lower part and the tool upper part. At least one measuring transducer, is provided between the tool upper part and the tool lower part and is in contact with at least one functional layer and/or an insulating layer of the multi-layer circuit board to be produced. A tool logic module and a measurement value transmission module with a receiving unit and with a transmission unit are provided. The tool logic module is retained on the tool and designed for receiving measurement values of the measuring transducer and wherein the tool logic module has a transmitter.

